

SLOVENSKI STANDARD
SIST EN 60749-15:2011/AC:2011
01-december-2011

**Polprevodniški elementi - Metode za mehansko in klimatsko preskušanje - 15. del:
Odpornost elementov, montiranih v skozijskih luknjah, proti spajkalni temperaturi**

Semiconductor devices - Mechanical and climatic test methods - Part 15: Resistance to soldering temperature for through-hole mounted devices

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 15:
Beständigkeit gegen Löttemperatur bei Bauelementen zur Durchsteckmontage

Dispositifs à semiconducteurs - Méthodes d'essai mécaniques et climatiques - Partie 15:
Résistance à la température de soudage pour dispositifs par trous traversants

<https://standards.iteh.ai/catalog/standards/sist/8789dff8-0808-4a40-a09a-ff2c7779a4dd/sist-en-60749-15-2011-ac-2011>

Ta slovenski standard je istoveten z: EN 60749-15:2010/AC:2011

ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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Corrigendum to EN 60749-15:2010

English version

Foreword

Delete the following sentence: "Annex ZA has been added by CENELEC."

February 2011

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